



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of: )  
Singh et al. ) Group Art Unit: 2811  
Application No. 10/633,021 ) Examiner: Vu, Hung K.  
Filed: 7/31/2003 ) Atty. Docket No. NVIDP235/  
For: PAD OVER ACTIVE CIRCUIT ) P000846  
SYSTEM AND METHOD WITH )  
FRAME SUPPORT STRUCTURE ) Date: December 2, 2004  
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)

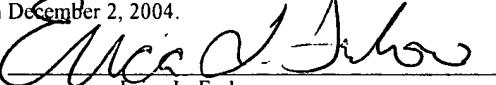
CERTIFICATE OF MAILING

12/07/2004 MBEYENE1 00000044 10633021

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I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on December 2, 2004.

Signed: 

Erica L. Farlow

INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR §§ 1.56 AND 1.97(C)

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

The references listed in the attached PTO Form 1449, copies of which are attached, may be material to examination of the above-identified patent application. Applicants submit these references in compliance with their duty of disclosure pursuant to 37 CFR §§ 1.56 and 1.97. The Examiner is requested to make these references of official record in this application.

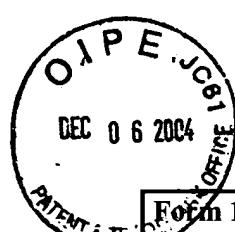
This Information Disclosure Statement is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that these references indeed constitute prior art.

This Information Disclosure Statement is being filed after the mailing date of a first Office Action. Accordingly, applicants are including a check in the amount of \$180.00 for the fee due in connection with the filing of this Information Disclosure Statement. However, if it is determined that any additional fees are due, the Commissioner is hereby authorized to charge such fees or credit any overpayment to Deposit Account 50-1351 (Order No.NVIDP235).

Respectfully submitted,  
Zilka-Kotab, PC

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Form 1449 (Modified)

**Information Disclosure  
Statement By Applicant**

(Use Several Sheets if Necessary)

Atty. Docket No.  
NVIDP235/P000846  
Applicant:  
Singh et al.  
Filing Date:  
7/31/2003

Application No.:  
10/633,021  
Group Art Unit:  
2811

**U.S. Patent Documents**

| Examiner Initial | No | Patent No. | Date       | Patentee           | Class | Sub-class | Filing Date |
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| Examiner         |    | Date Considered  |

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

|  |  |  |  |                                      |                                |  |
|--|--|--|--|--------------------------------------|--------------------------------|--|
| <b>Form 1449 (Modified)</b>                              |  |  |  | Atty. Docket No.<br>NVIDP235/P000846 | Application No.:<br>10/633,021 |  |
| <b>Information Disclosure<br/>Statement By Applicant</b> |  |  |  | Applicant:<br>Singh et al.           |                                |  |
| (Use Several Sheets if Necessary)                        |  |  |  | Filing Date:<br>7/31/2003            | Group Art Unit:<br>2811        |  |

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|                  | MM  |            |            |                    |       |           |             |
|                  | NN  |            |            |                    |       |           |             |
|                  | OO  |            |            |                    |       |           |             |
|                  | PP  |            |            |                    |       |           |             |

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| Examiner         |     | Date Considered  |

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.